



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Sectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2021-06-16
Company Unique ID	NL 008751171B01		
Authorized Representative *	PERILLAT	Representative Title	Group Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STDP2600-AC/AD/AE STDP2650-AC/AD /AE STDP2690-AC/AD /AE	MCP5*2650AEM MCP5*2600AEM MCP5*2690AEM	A	0959	2021-06-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	162.0	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
SACN306	NAC	Copper Alloy	1F032095/ CD00371144 4.0	

Package Designator	Size	Nbr of instances	Shape
LFBGA	8 x 8	81	SQUARE
Comment	LFBGA 8X8X1.4 81 F9X9 P0.8 B0.5		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
,	
,	
,	

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirement without any exemptions	true
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)	false
Exemption Id.	Description
,	
,	
,	

QueryList : California Prop65 list, dated 19th March 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			false
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.301	no exposure to consumers is foreseen	1858
Lead	0.004	no exposure to consumers is foreseen	25

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-19th January 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,				
,				
,				
,				
,				
,				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Homogeneous Material (mg)	Application - Homogeneous Material	ppm in Homogeneous Material
,				
,				
,				
,				
,				
,				

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				false
Substance present in device Homogeneous Material				
Substance	Homogeneous Material impacted	Content in Homogeneous Material (mg)	Concentration in the material(%)	Application Purpose

Bromine		0		

Material Composition Declaration						Mfr Item Name	MCPS*2650AEM MCPS*2600AEM MCPS*2690AEM		162.0005		6000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.330	mg	supplier	die	Silicon(Si)	7440-21-3		3.108	mg	933333	19185
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.015	mg	4505	93
				supplier	metallisation	Copper(Cu)	7440-50-8		0.093	mg	27928	574
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.016	mg	4805	99
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.004	mg	1201	25
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	300	6
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.021	mg	6306	130
				supplier	passivation	Silicon Oxide	7631-86-9		0.072	mg	21622	444
				supplier	laminiate	Bismaleimide (B)	105391-33-1		1.793	mg	29824	11068
				supplier	laminiate	Triazine (T)	25722-66-1		1.793	mg	29824	11068
Substrate	M-015 Other organic materials	60.119	mg	supplier	laminiate	Fiber glass	65987-17-3		5.350	mg	88990	33025
				supplier	laminiate	Thermosetting resin	54208-63-8		3.003	mg	49951	18537
				supplier	laminiate	metal hydroxide	21645-51-2		0.122	mg	2029	753
				supplier	laminiate	Calcium sulfate	7778-18-9		0.061	mg	1015	377
				supplier	laminiate	Zinc hydroxide	20427-58-1		0.037	mg	615	228
				supplier	laminiate	Barium sulfate	7727-43-7		0.312	mg	5190	1926
				supplier	laminiate	Acrylic resin	9003-01-4		0.483	mg	8034	2981
				supplier	laminiate	Epoxy resin	29690-82-2		0.380	mg	6321	2346
				supplier	laminiate	Biphenyl epoxy resin	85954-11-6		0.235	mg	3908	1451
				supplier	laminiate	Talc containing no asbestiform fibers	14807-96-6		0.181	mg	3011	1117
				supplier	laminiate	Methoxymethylethoxy propanol	34590-94-8		0.052	mg	865	321
				supplier	laminiate	Amorphous silica	7631-86-9		0.035	mg	582	216
				supplier	laminiate	3-methyl-methoxy-butyl	103429-90-9		0.023	mg	383	142
				supplier	laminiate	Silica Cristobalite	14464-46-1		0.017	mg	283	105
				supplier	laminiate	Copper Phthalocyanine	14302-13-7		0.001	mg	17	6
				supplier	laminiate	Morpholine derivative	Proprietary		0.009	mg	150	56
				supplier	laminiate	Copper (Cu)	7440-50-8		45.910	mg	763651	283394
				supplier	laminiate	Nickel (Ni)	7440-02-0		0.285	mg	4741	1759
				supplier	laminiate	Gold (Au)	7440-57-5		0.037	mg	615	228
				Die attach	M-015 Other organic materials	1.044	mg	supplier	glue	Silver (Ag)	7440-22-4	
supplier	glue	Neopentyl glycol dimethacrylate	1985-51-9						0.052	mg	49808	321
supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1						0.052	mg	49808	321
supplier	glue	Ditrimethylolpropane tetraacrylate	94108-97-1						0.016	mg	15326	99
supplier	glue	Hydroquinone	123-31-9						0.001	mg	958	6
supplier	glue	palmitic acid	57-10-3						0.001	mg	958	6
supplier	glue	4-tert-butylcyclohexanol	98-52-2						0.003	mg	2874	19
supplier	glue	Hexamethyltetraacosa-hexaene	111-02-4						0.001	mg	958	6
Bonding wire	M-008 Precious metals	1.164	mg	supplier	wire	Gold (Au)	7440-57-5		1.152	mg	989691	7111
				supplier	wire	Palladium (Pd)	7440-05-3		0.012	mg	10309	74
Encapsulation	M-015 Other organic materials	56.581	mg	supplier	mold compound	Silica, vitreous	80676-86-0		46.113	mg	814991	284648
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		5.658	mg	99998	34926
				supplier	mold compound	Phenol resin	205830-20-2		2.829	mg	49999	17463
				supplier	mold compound	Magnesium dihydroxide	1309-42-8		0.057	mg	1007	352
				supplier	mold compound	Quartz	14808-60-7		1.415	mg	25008	8735
				supplier	mold compound	Carbon Black	1333-86-4		0.509	mg	8996	3142
Solder balls	Solder	39.762	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		38.298	mg	963181	236407
				supplier	solder alloy	Silver (Ag)	7440-22-4		1.193	mg	30004	7264
				supplier	solder alloy	Copper (Cu)	7440-50-8		0.239	mg	6011	1475
				supplier	solder alloy	Nickel (Ni)	7440-02-0		0.016	mg	402	99
				supplier	solder alloy	Antimony (Sb)	7440-36-0		0.012	mg	302	74
				JIG - R	solder alloy	Lead (Pb)	7439-92-1		0.004	mg	101	25